

On page 4, line 23, after the word "because", please insert --of--.

On page 8, line 22, before the word "combination", please delete "the" and insert in its place --any--.

On page 12, line 23, please delete "FIG. 7B" and insert in its place --FIGS. 3M and 7B--.

In The Claims

~~Please amend claims 28 and 30 as follows:~~

- C1 and C2*
28. (AMENDED) An interconnect structure comprising:
a plurality of metal lines formed on a substrate;
low-k dielectric structures interposed between two or more of said metal lines;
a second dielectric material formed above said metal lines;
a protective layer interposed between said low-k dielectric structures and said second dielectric material, wherein said protective layer is configured to provide etch selectivity between said protective layer and said second dielectric material; and
a conductive feature formed within said second dielectric material and said protective layer, said conductive feature in contact with at least one of said plurality of metal lines.

- C2*
30. (AMENDED) The interconnect structure according to claim 28, further comprising a liner disposed within a feature formed within said second dielectric material.

REMARKS

In the May 30, 2000 Office Action, the Examiner rejected claims 16-33 pending in the application. This Response amends claims 28 and 30. After entry of the foregoing